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**AMENDMENTS TO THE CLAIMS** 

This listing of claims will replace all prior versions and listings of claims in the

application:

LISTING OF CLAIMS:

Claims 1 and 2 (canceled).

3. (currently amended) The semiconductor device as claimed in claim 2, A

semiconductor device comprising:

a first resin package comprising:

a semiconductor chip;

a chip electrode on a surface of said semiconductor chip;

a first resin sealing said semiconductor chip; and

a first package electrode on a surface of said first resin being electrically

connected to said chip electrode, said first package electrode comprising a mounting pad

and a testing pad provided apart from said mounting pad and said testing pad enabling

electrical measurement of said semiconductor chip without using said mounting pad;

a mounted object connected to said mounting pad, and

a wiring connecting said mounting pad to said mounting object,

wherein said mounting pad is arranged along an edge of said first resin package, and

wherein said testing pad is arranged at an inner position with respect to said mounting

pad.

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4. (original) The semiconductor device as claimed in claim 3, further comprising: a second resin sealing said first resin package and a first surface of said mounted object.

5. (previously presented) The semiconductor device as claimed in claim 4, further comprising:

an inner wiring connecting said chip electrode to said mounting pad.

6-12. (withdrawn)

13. (currently amended) The semiconductor device as claimed in claim  $4 \underline{3}$ , wherein said mounted object is a mounting substrate.

14-20. (withdrawn)

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## <u>REMARKS</u>

Claims 3-5 and 13 are all the claims pending in the application. Claims 1 and 2 are canceled. Claims 6-12 and 14-20 have been withdrawn from consideration as the result of a restriction requirement.

Applicant first notes that on page 2 of the Office Action, the Examiner identifies Hayashida et al. as U.S. Patent No. 5,963,433. This appears to be an error because the PTO-892 lists Hayashida et al. as U.S. Patent No. 6,060,768.

Applicant thanks the Examiner for indicating that claims 3-5 would be allowable if rewritten in independent form. Applicant has rewritten claim 3 in independent form. Therefore, claims 3-5 should be allowable.

Applicant has also amended claim 13 so that it depends from claim 3. Therefore, it should also be allowable based on its dependence from claim 3.

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

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The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,

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